# <SPECIFICATION>

SPEC.No. ASDIQ-SPE-043(00)
Date: Jan. 7, 2022

**To :**

| CUSTOMER'S PRODUCT NAME |
|---|
| |

| ASDI PRODUCT NAME: |
|---|
| AMPI4030B-Series |

RECEIPT CONFIRMATION

| UNCONDITIONAL CONSENT | CONDITIONAL CONSENT |
|---|---|
| | |

| APPROVED | CHECKED |
|---|---|
| | |

ASDI SIGNATURE

| APPROVED | CHECKED | PREPARED |
|---|---|---|
| Xianglong Li | Liang Wang | Jiayin Cai |

| REV. | DATE | DESCRIPTION | APPROVED | CHECKED | PREPARED |
|---|---|---|---|---|---|
| 00 | Jan. 7, 2022 | New release | Xianglong Li | Liang Wang | Jiayin Cai |
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# CAUTION WHEN HANDLING

Before use the products, please read this specification.

# CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

# CAUTION

*The product should be used within 12 monthes.
Focus on the storage conditions.
Solderability may become weak if it exceeds the period.
*Do not use and store the product in condition of gas corrosion (Salt,Acid,Alkaline).
*The products must be preheated before soldering.
The operating temperature including self-generated heat must be within '- 25 ~ +125℃.
*Rework by soldering iron;Please keep the mentioned conditions in this specification.
*In case of insert P.C. Board on chassis, do not add mechanical stress to the product.
*Be careful to arrange of non-magnetic field type inductors.
The error may be caused by magnetic field coupling.
*In case handle the products, please use wrist strap for ground static discharge on human body.
The product keeps away from magnet or magnetized things.
*Do not use the product beyond the mentioned conditions in this specification.
*About an application
The products listed on this specification sheet are intended for use in general electronic equipment
(AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.
*The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

1)Aerospace/Aviation equipment
2)Military equipment
3)Seabed equipment
4)Safety equipment
5)Medical equipment
6)Transportation control equipment
7)Power-generation control equipment which directly endanger human life
8)Atomic energy-related equipment
9)Other applications that are not considered general-purpose applications

If you intend to use the products in the following applications, please contact our sales office.
Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment
When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

1.INDEX



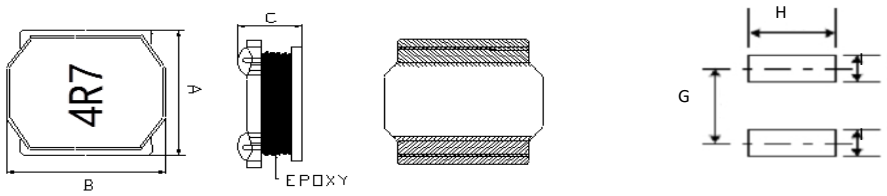
2.Manufacturing Location

China

(1)Features

1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.

(2)Dimensions




Units: mm

| Series | A(mm) | B(mm) | C(mm) | G(mm) | H(mm) | I(mm) |
|---|---|---|---|---|---|---|
| AMPI4030B | 4.0±0.2 | 4.0±0.2 | 3.0 max. | 2.8 ref. | 3.7 ref. | 1.2 ref. |

(3)Part Numbering

| AMPI | 4030 | B | - | 2R2 | M |
|---|---|---|---|---|---|
| A | B | C | | D | E |

A: Series
B: Dimension
C: Control S/N
D: Inductance 2R2=2.2μH
E: Inductance Tolerance M=±20%, N=±30%;

(4)Electrical Specifications

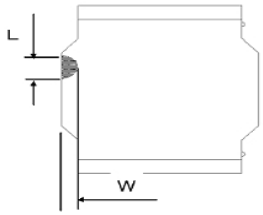
Table 1

| ASDI Part Number | Inductance (μH) | Tolerance (%) | Test Frequency | SRF (MHz) min. | DCR (Ω) ±30% | I sat (A) | I rms (A) |
|---|---|---|---|---|---|---|---|
| AMPI4030B-1R0N | 1.0 | ±30% | 100kHz/1V | 90 | 0.025 | 4.70 | 3.35 |
| AMPI4030B-1R5N | 1.5 | ±30% | 100kHz/1V | 90 | 0.030 | 4.55 | 3.20 |
| AMPI4030B-2R2M | 2.2 | ±20% | 100kHz/1V | 60 | 0.038 | 4.40 | 2.95 |
| AMPI4030B-3R3M | 3.3 | ±20% | 100kHz/1V | 45 | 0.052 | 3.30 | 2.40 |
| AMPI4030B-4R7M | 4.7 | ±20% | 100kHz/1V | 35 | 0.065 | 2.90 | 2.00 |
| AMPI4030B-6R8M | 6.8 | ±20% | 100kHz/1V | 30 | 0.095 | 2.65 | 1.60 |
| AMPI4030B-100M | 10.0 | ±20% | 100kHz/1V | 25 | 0.110 | 1.95 | 1.50 |
| AMPI4030B-150M | 15.0 | ±20% | 100kHz/1V | 18 | 0.198 | 1.65 | 1.20 |
| AMPI4030B-220M | 22.0 | ±20% | 100kHz/1V | 15 | 0.270 | 1.30 | 1.00 |
| AMPI4030B-330M | 33.0 | ±20% | 100kHz/1V | 12 | 0.420 | 1.00 | 0.81 |
| AMPI4030B-470M | 47.0 | ±20% | 100kHz/1V | 8.0 | 0.430 | 0.93 | 0.72 |
| AMPI4030B-680M | 68.0 | ±20% | 100kHz/1V | 5.0 | 0.930 | 0.80 | 0.42 |

Note:
Isat：Based on inductance change （△L/L0：≦-30%）@ ambient temp. 25℃
Irms：Based on temperature rise （△T：40℃ typ.）

Core chipping

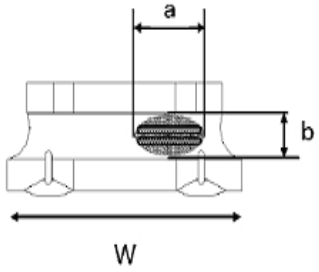
The appearance standard of the chipping size in top side, of bottom side ferrite core is following dimension.




| Type | L | W |
|---|---|---|
| AMPI4030B | 1.5mm Max. | 1.5mm Max. |

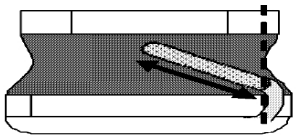
Vacant appearance tolerance Limit

Size of voids occurring to coating resin is specified below.




External appearance criterion for exposed wire

Exposed end of the winding wire at the secondary side should be 2mm and below.



Exposed wire tolerance limit of coating resin part on product side.

Size of exposed wire occurring to coating resin is specified below.

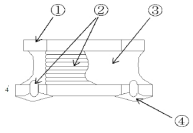
1.Width direction(dimension a): Acceptable when a≦1/2W

Nonconforming when a＞1/2W

2.Length direction(dimension b): Dimension b is not specified.

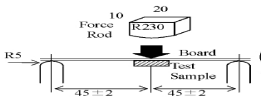
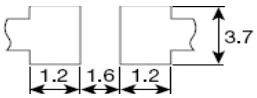
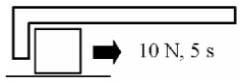
3.When total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, that is acceptable.

(5)Material List



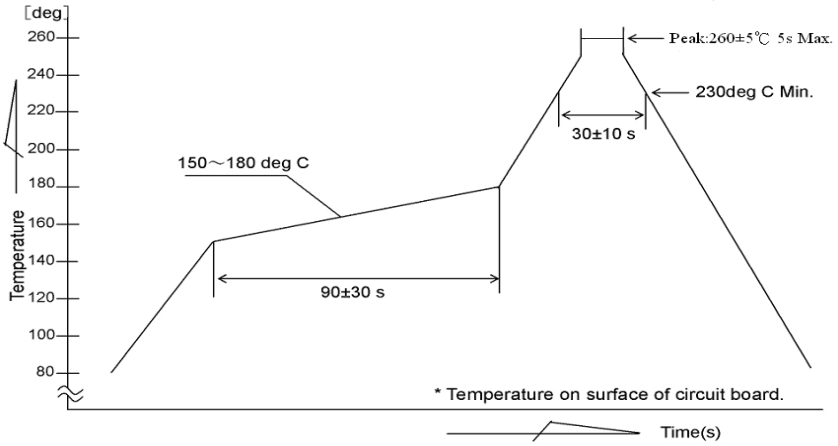

| NO | Items | Materials |
|---|---|---|
| 1 | Core | Ni-Zn ferrite |
| 2 | Wire | Copper Wire |
| 3 | Coating | Epoxy |
| 4 | Solder | Lead free |

(6)Reliability Tests

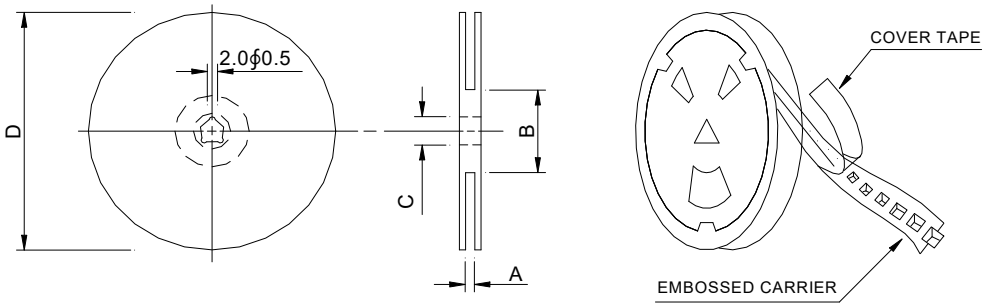
| No. | Test item | Performance | Test details |
|---|---|---|---|
| 1 | Operating temperature | - 25 ~ +125℃. | Including self-generated heat |
| 2 | Storage temperature and Humidity range | -40 ~ +85℃.<br>- 5 to 40℃ for the product with taping. | |
| 3 | Rated current | Within the specified tolerance | |
| 4 | Inductance (L) | | LCR Meter: HP 4285A or equivalent, 100kHz, 1V |
| 5 | DC Resistance | | DC Ohmmeter: HIOKI3227 or equivalent |
| 6 | Temperature characteristics | Inductance change：Within±20% | Measurement of inductance shall be taken at temperature rang within–25℃ to +85℃.<br>With reference to inductance value at+20 ℃,change rate shall be calculated.<br>Measurement of inductance shall be taken at temperature rang within–40℃ to +125℃.<br>With reference to inductance value at+20 ℃,change rate shall be calculated. |
| 7 | Resistance to flexure substrate | No damage | The test samples shall be soldered to the testing board by the reflow.<br>As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2mm.<br>  <br><br>Substrate size：100x40x1.0<br>Substrate material：glass epoxy-resin<br>Solder cream thickness：0.15<br>  <br> |
| 8 | Adhesion of Terminal electrode | Shall not come off PC board. | The test samples shall be soldered to the testing board and by the reflow.<br>  <br><br>Applied force：10 N to X and Y directions.<br>Duration：5s<br>Solder cream thickness：0.15 |
| 9 | Resistance to Vibration | Inductance change：Within±10%<br>No abnormality observed in appearance. | The test samples shall be soldered to the test board by the reflow.<br>Then it shall be submitted to below test conditions.<br>Frequency: 10-55Hz<br>Total Amplitude: 1.5mm (May not exceed acceleration 196m/S2 )<br>Sweeping Method:10Hz to 55Hz to 10Hz for 1min.<br>Time：2 hours each in X,Y, and Z Direction.<br>Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs. |

<table>
<tr><th>No.</th><th>Test item</th><th>Performance</th><th>Test details</th></tr>
<tr><td>10</td><td>Solderability</td><td>At least 90% of surface of terminal electrode is covered by new solder.</td><td>The test samples shall be dipped in flux, and then immersed in molten solder as shown in below.<br>Flux：methanol solution containing rosin 25%<br>Solder temperature: 245±5℃<br>Time: 5±1.0 sec.<br>Immersion depth: All sides of mounting terminal shall be immersed.</td></tr>
<tr><td>11</td><td>Resistance to soldering</td><td>Inductance change：Within±10%<br>No abnormality observed in appearance.</td><td>The test sample shall be exposed to reflow oven at 230±5℃ for 40 seconds, with peak temperature at 260±5℃ for 5 seconds,2 times.<br>Test board thickness: 1.0mm<br>Test board material: glass epoxy-resin</td></tr>
<tr><td>12</td><td>Thermal shock</td><td rowspan="5">Inductance change：Within±10%<br>No abnormality observed in appearance.</td><td>The test samples shall be soldered to the test board by the reflow.<br>The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown below in sequence.<br>The temperature cycles shall be repeated 100 cycles .<br><table><tr><th>Phase</th><th>Temperature(℃)</th><th>Time(min.)</th></tr><tr><td>1</td><td>-40±3℃</td><td>30±3</td></tr><tr><td>2</td><td>Room Temp</td><td>Within 3</td></tr><tr><td>3</td><td>85±2℃</td><td>30±3</td></tr><tr><td>4</td><td>Room Temp</td><td>Within 3</td></tr></table></td></tr>
<tr><td>13</td><td>Damp heat life test</td><td>Test Method and Remarks The test samples shall be soldered to the test board by the reflow.<br>The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below.<br>Temperature: 60±2℃<br>Humidity: 90~95%RH<br>Time: 500+24/-0 hrs</td></tr>
<tr><td>14</td><td>Loading under damp heat life test</td><td>The test samples shall be soldered to the test board by the reflow.<br>The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below.<br>Temperature: 60±2℃<br>Humidity: 90~95%RH<br>Applied current: Rated current<br>Time: 500+24/-0 hrs</td></tr>
<tr><td>15</td><td>Low temperature life test</td><td>The test samples shall be soldered to the test board by the reflow.<br>After that, the test samples shall be placed at test conditions as shown in below.<br>Temperature:-40±2℃<br>Time:500+24/-0 hrs</td></tr>
<tr><td>16</td><td>Loading at high temperature life test</td><td>The test samples shall be soldered to the test board by the reflow.<br>Temperature: 85±2℃.<br>Applied current: Rated current<br>Time: 500+24/-0 hrs.</td></tr>
</table>

(7)Soldering

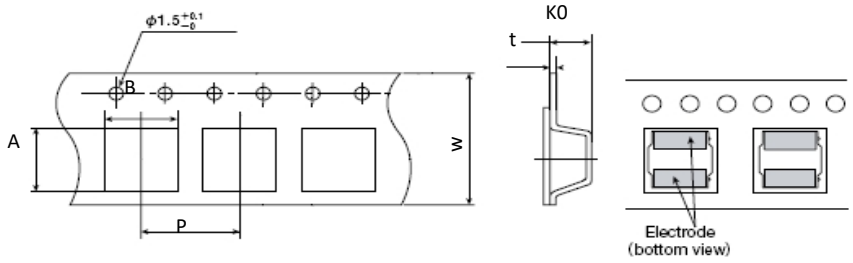



(8)Packaging Information
8-1,Reel Dimension




| Type | A(mm) | B(mm) | C(mm) | D(mm) |
|---|---|---|---|---|
| AMPI4030B | 12.4±2.0 | 100±4.0 | 13.2±0.2 | 330±2.0 |

8-2,Tape Dimension




| Series | A(mm) | B(mm) | Ko(mm) | P(mm) | W(mm) | t(mm) |
|---|---|---|---|---|---|---|
| AMPI4030B | 4.25±0.1 | 4.25±0.1 | 3.25±0.1 | 8.0±0.1 | 12.0±0.3 | 0.4±0.05 |

8-3,Packaging Quantity

| Type | Chip / Reel |
|---|---|
| AMPI4030B | 2000 |

(9)Note

·Storage Conditions

To maintain the solderability of terminal electrodes:

1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.
3. Recommended products should be used within 12 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

·Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.